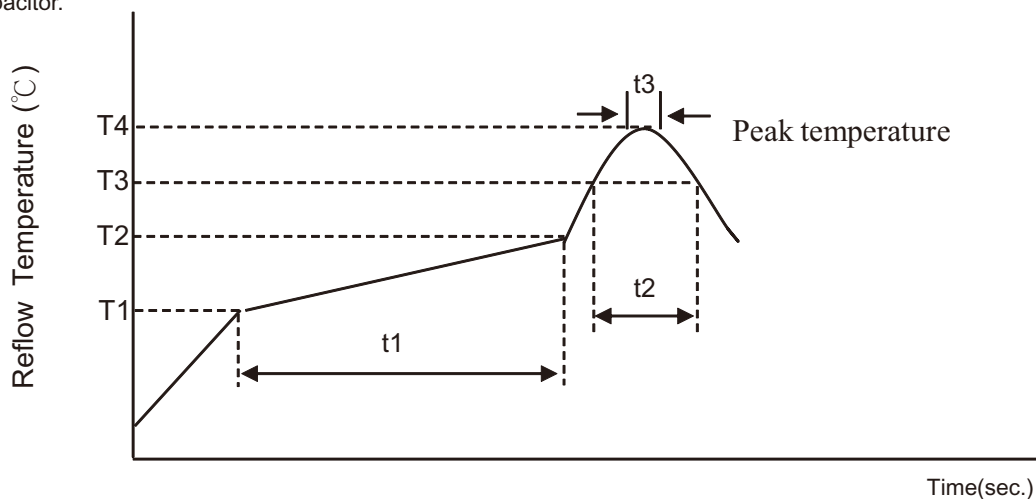


鋁電解電容器使用需知

RECOMMENDED PB-FREE REFLOW SOLDERING CONDITIONS

The following conditions are recommended for air or infrared reflow soldering of the surface mount capacitors onto a glass epoxy circuit board of 95 x 50 x 0.8mm (with resist) by cream solder (eutectic solder). The temperatures shown are the surface temperature values of the top of the capacitor.



TEMPERATURE PROFILE

Profile Feature	Pb Free Assembly	
	4~6.3Ø	8~10Ø
Average Ramp-up Rate	3°C/second max.	3°C/second max.
Preheat		
Temperature Min(T1 min)	150°C	150°C
Temperature Max(T2 max)	180°C	180°C
Time (t1 Max)	120sec.	120sec.
Ramp-up Rate (T2 ~T3)	3°C/second max.	3°C/second max.
Time maintained above		
Temperature(T3)	217°C	217°C
Time(t2 Max)	90sec.	40sec.
Peak Temperature(T4)	260°C	245°C
Time(t3 Max)	5sec.	5sec.
Reflow cycles	1	2 or less